

# 2SJ0364 (2SJ364)

## Silicon P-channel junction FET

For analog switch circuits

### ■ Features

- Low ON resistance
- Low-noise characteristics

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter                    | Symbol           | Rating      | Unit             |
|------------------------------|------------------|-------------|------------------|
| Gate-drain surrender voltage | $V_{\text{GDS}}$ | 65          | V                |
| Drain current                | $I_{\text{D}}$   | -20         | mA               |
| Gate current                 | $I_{\text{G}}$   | -10         | mA               |
| Power dissipation            | $P_{\text{D}}$   | 150         | mW               |
| Channel temperature          | $T_{\text{ch}}$  | 150         | $^\circ\text{C}$ |
| Storage temperature          | $T_{\text{stg}}$ | -55 to +150 | $^\circ\text{C}$ |

### ■ Package

- Code  
SMini3-G1
- Pin Name  
1: Source  
2: Drain  
3: Gate

### ■ Marking Symbol: 4M

### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

| Parameter  | Symbol              | Conditions  | Min  | Typ | Max  | Unit     |
|--|---------------------|---|------|-----|------|----------|
| Gate-drain surrender voltage                               | $V_{\text{GDS}}$    | $I_{\text{G}} = 10 \mu\text{A}$ , $V_{\text{DS}} = 0$                               | 65   |     |      | V        |
| Drain-source current *                                     | $I_{\text{DSS}}$    | $V_{\text{DS}} = -10 \text{V}$ , $V_{\text{GS}} = 0$                                | -0.6 |     | -6.0 | mA       |
| Gate-source cutoff current                                 | $I_{\text{GSS}}$    | $V_{\text{GS}} = 30 \text{V}$ , $V_{\text{DS}} = 0$                                 |      |     | 10   | nA       |
| Gate-source cutoff voltage                                 | $V_{\text{GSC}}$    | $V_{\text{DS}} = -10 \text{V}$ , $I_{\text{D}} = -10 \mu\text{A}$                   |      | 1.5 | 3.5  | V        |
| Forward transfer admittance                                | $ Y_{\text{fs}} $   | $V_{\text{DS}} = -10 \text{V}$ , $I_{\text{D}} = -1 \text{mA}$ , $f = 1 \text{kHz}$ | 1.8  | 2.5 |      | mS       |
| Short-circuit forward transfer capacitance (Common source) | $C_{\text{iss}}$    | $V_{\text{DS}} = -10 \text{V}$ , $V_{\text{GS}} = 0$ , $f = 1 \text{MHz}$           |      | 12  |      | pF       |
| Reverse transfer capacitance (Common source)               | $C_{\text{rss}}$    |   |      | 4   |      | pF       |
| Drain-source ON resistance                                 | $R_{\text{DS(on)}}$ | $V_{\text{DS}} = -10 \text{mV}$ , $V_{\text{GS}} = 0$                               |      | 300 |      | $\Omega$ |

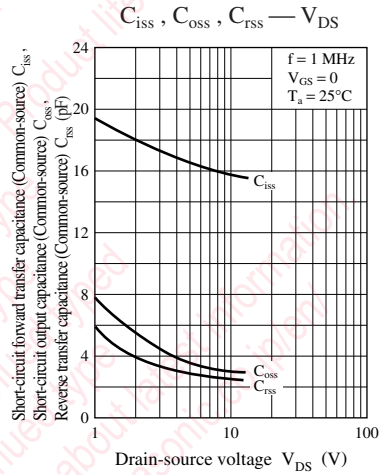
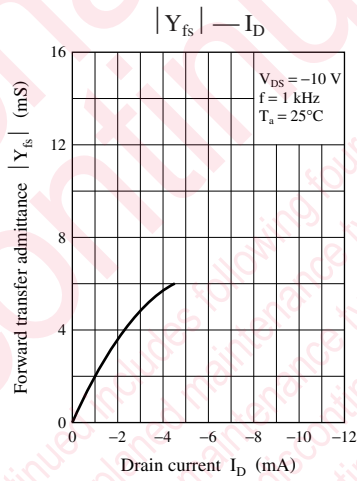
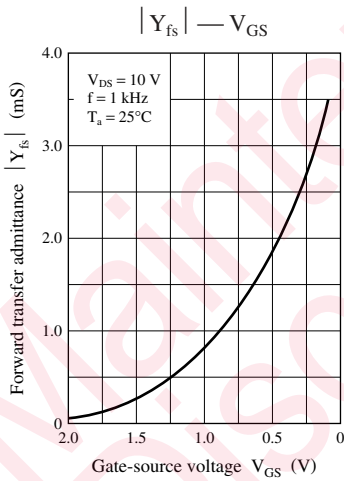
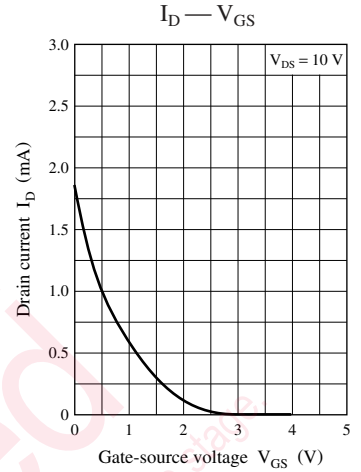
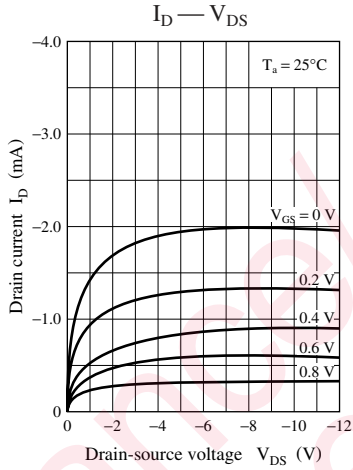
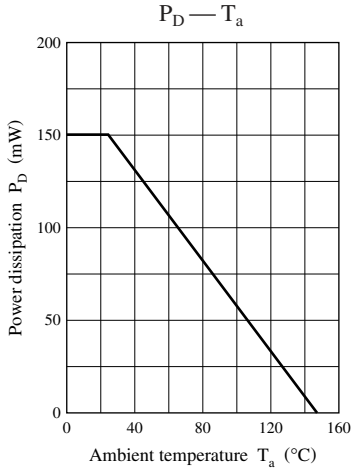
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. Observe precautions for handling. Electrostatic sensitive devices.

3. \*: Rank classification

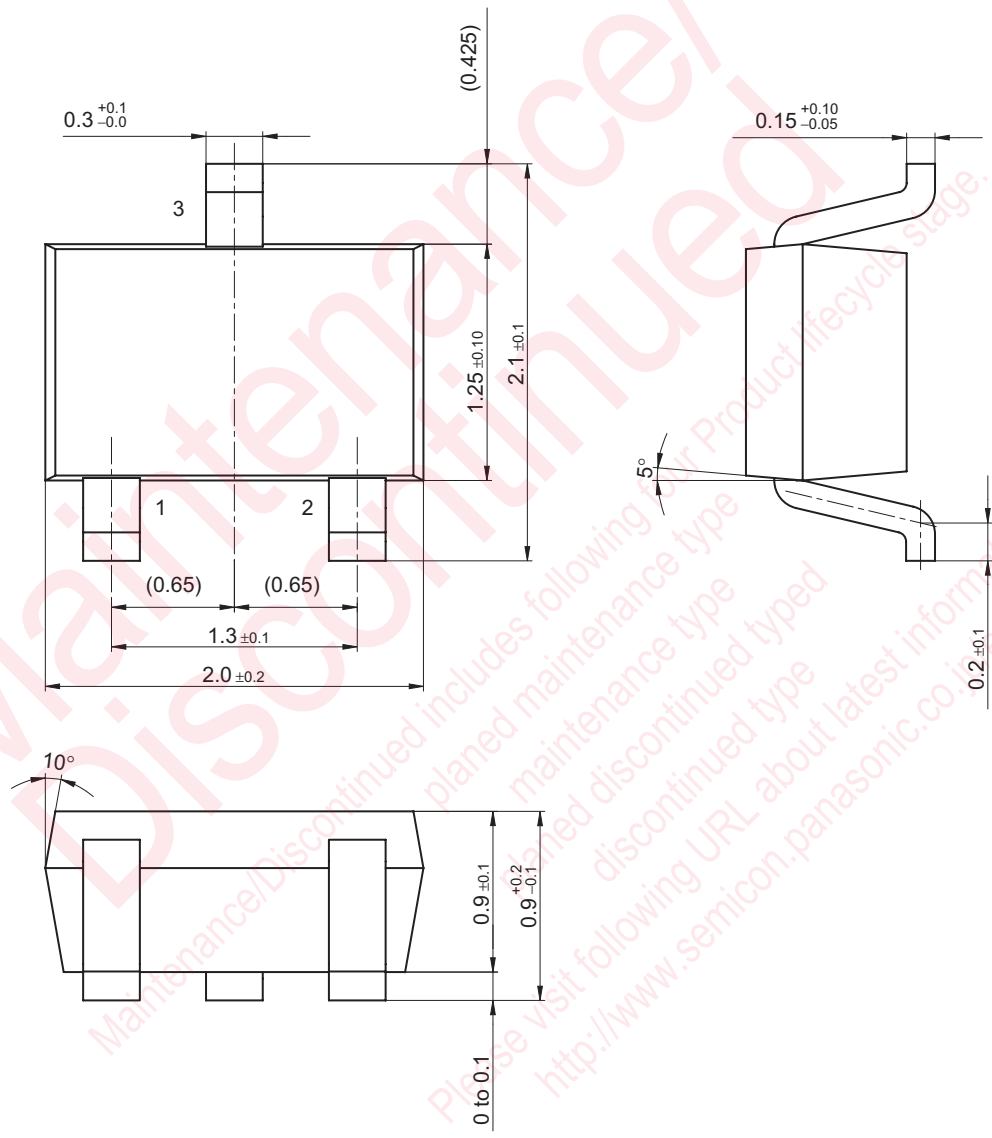
| Rank                  | P            | Q            | R            |
|-----------------------|--------------|--------------|--------------|
| $I_{\text{DSS}}$ (mA) | -0.6 to -1.5 | -1.0 to -3.0 | -2.5 to -6.0 |

Note) The part number in the parenthesis shows conventional part number.



SMini3-G1

Unit: mm



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